

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

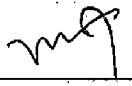

EPAS ID: PAT3947055

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|---|---|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| WEI MA | 11/03/2014 |
| WAI HUNG | 11/03/2014 |
| FRANCIS GUILLEN GAMBOA | 11/03/2014 |
| XIAOMING YU | 11/03/2014 |
| DENNIS TAK KIT TONG | 11/03/2014 |
| RECEIVING PARTY DATA | |
| Name: | SAE MAGNETICS (H.K.) LTD. |
| Street Address: | SAE TECHNOLOGY CENTRE, 6 SCIENCE PARK EAST AVENUE, HONG KONG SCIENCE PARK, SHATIN, N.T. |
| City: | HONG KONG |
| State/Country: | HONG KONG |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 15201519 |
| CORRESPONDENCE DATA | |
| Fax Number: | |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Email: | charles_ho@barron-young.com |
| Correspondent Name: | B.Y.I.P., LTD |
| Address Line 1: | P.O. BOX 1484 OF GENERAL POST OFFICE |
| Address Line 4: | HONG KONG, HONG KONG |
| ATTORNEY DOCKET NUMBER: | SAE-1604-USCON |
| NAME OF SUBMITTER: | CHARLES S. HO |
| SIGNATURE: | /charles ho/ |
| DATE SIGNED: | 07/05/2016 |
| Total Attachments: 5 | |
| source=Executed Assignment_SAE-1604-USCON (00498737)#page1.tif | |
| source=Executed Assignment_SAE-1604-USCON (00498737)#page2.tif | |
| source=Executed Assignment_SAE-1604-USCON (00498737)#page3.tif | |


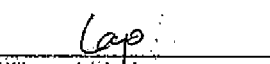
source=Executed Assignment_SAE-1604-USCON (00498737)#page4.tif

source=Executed Assignment_SAE-1604-USCON (00498737)#page5.tif

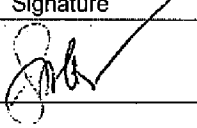
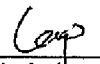
| | | |
|--|--|--------------------------------------|
| ASSIGNMENT - Patent Application | | Docket Number: <u>SAE-1604-USCON</u> |
| Whereas, the Assignor, comprising the following named inventors: | | |
| ASSIGNOR(s)/ INVENTOR(s) | Wei Ma | |
| made an invention entitled: <u>WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME</u> | | |
| for which an application for Letters Patent of the United States: (Select one of the following): | | |
| <input checked="" type="checkbox"/> is executed concurrently herewith <input type="checkbox"/> was filed in the U.S. Patent and Trademark Office on _____, as U.S. Patent Application Serial No.: _____ | | |
| ASSIGNEE (Full Name, Address and Country) | SAE Magnetics (H.K.) Ltd. SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T. Hong Kong | |
| is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor, Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto. Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment. Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument. In witness whereof, this Assignment is executed on the day indicated below. | | |

| | Typed or Printed Name | Signature | Date |
|-----------|-----------------------|---|-------------|
| SIGNATURE | Wei Ma | X  | X 3-11-2014 |
| | KA LAP TONG | X  | X 3-Nov-14 |
| | * Witness to Assignor | * Witness to Assignor | |

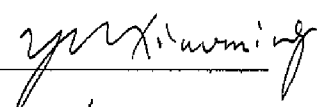
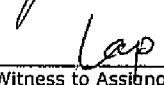
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| SIGNATURE | Wai Hung | X  | X 3-Nov-2014 |
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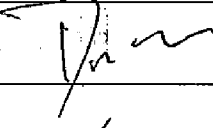
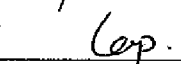
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| | Typed or Printed Name | Signature | Date |
|-----------|------------------------|--|---------------|
| SIGNATURE | Francis Guillen Gamboa | X  | X 03 NOV-2014 |
| | KA LAP, TONG | X  | X 8-Nov-14 |
| | * Witness to Assignor | * Witness to Assignor | |

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| ASSIGNMENT - Patent Application | | Docket Number: SAE-1604-USCON |
| Whereas, the Assignor, comprising the following named inventors: | | |
| ASSIGNOR(s)/ INVENTOR(s) | Xiaoming Yu | |
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| ASSIGNEE (Full Name, Address and Country) | SAE Magnetics (H.K.) Ltd. SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T. Hong Kong | |
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| | Typed or Printed Name | Signature | Date |
|-----------|-----------------------|--|--------------|
| SIGNATURE | Xiaoming Yu | X  | X 3/Nov/2014 |
| | KA LAP TONG | X  | X 3-Nov-14 |
| | * Witness to Assignor | * Witness to Assignor | |

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| | Typed or Printed Name | Signature | Date |
|-----------|----------------------------|---|-------------------|
| SIGNATURE | Dennis Tak Kit Tong | X  | X <u>3-Nov-14</u> |
| | <u>KA LAP TONG</u> | X  | X <u>3-Nov-14</u> |
| | * Witness to Assignor | * Witness to Assignor | |